



Click [here](#) for the 3D model.

| Dimensions |                 |
|------------|-----------------|
| Chip Size  | 2220            |
| L          | 5.9mm +/-0.4mm  |
| W          | 5mm +/-0.4mm    |
| T          | 2mm +/-0.20mm   |
| B          | 0.6mm +/-0.35mm |

  

| Packaging Specifications |                          |
|--------------------------|--------------------------|
| Packaging                | T&R, 330mm, Plastic Tape |
| Packaging Quantity       | 2000                     |

| General Information |  |
|---------------------|--|
| Series              | KC-LINK Comm COG                           |
| Style               | SMD Chip                                   |
| Description         | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features            | Ultra-Stable, Low Loss, Class I            |
| RoHS                | Yes  |
| Termination         | Tin  |
| Marking             | No   |
| AEC-Q200            | No   |
| Component Weight    | 260 mg                                     |
| Shelf Life          | 78 Weeks                                   |
| MSL                 | 1  |

| Specifications   |                        |
|--|------------------------|
| Capacitance  | 5100 pF                |
| Measurement Condition  | 1 kHz 1.0Vrms          |
| Capacitance Tolerance  | 1%                     |
| Voltage DC   | 650 VDC                |
| Dielectric Withstanding Voltage                                    | 845 VDC                |
| Temperature Range  | -55/+150°C             |
| Temperature Coefficient  | COG                    |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1kHz 1.0Vrms      |
| Aging Rate   | 0% Loss/Decade Hour    |
| Insulation Resistance  | 100 GOhms              |